

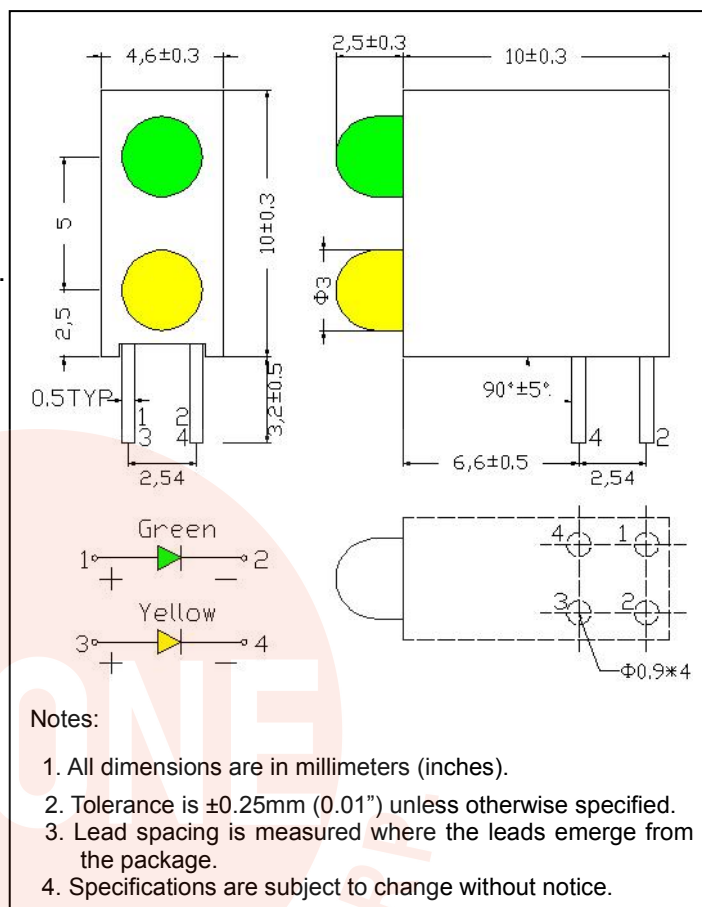
● Features:

1. Chip material: Gap(Green)
and AllnGap(Yellow)
2. Emitted color : Green and Yellow
3. Lens Appearance :Green Diffused
and Yellow Diffused
4. Designed for ease in circuit board assembly.
5. Black case enhance contrast ratio.
6. Solid state light source.
7. Reliable and rugged.
8. This product don't contained restriction
substance, compliance RoHS standard.

- **Applications:**

1. TV set
2. Monitor
3. Telephone
4. Computer
5. Circuit board

● Package dimensions



● **Absolute Maximum Ratings(Ta=25℃)**

Parameter	Symbol	Green	Yellow	Unit
Power Dissipation	Pd	75	75	mW
Forward Current	I _F	30	30	mA
Peak Forward Current* ¹	I _{FP}	50	50	mA
Reverse Voltage	V _R	5		V
Operating Temperature	Topr	-30℃~80℃		
Storage Temperature	Tstg	-40℃~85℃		
Soldering Temperature	Tsol	260℃max (for 5 seconds)		
Hand Soldering Temperature	Tsol	350℃max(for 3 seconds)		

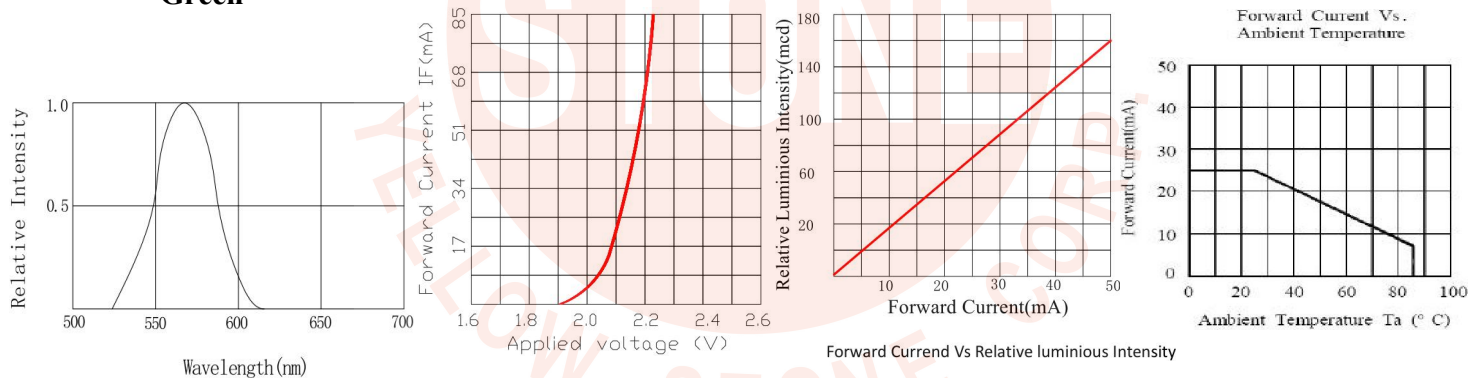
*¹Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width.

● Electrical and optical characteristics(Ta=25°C)

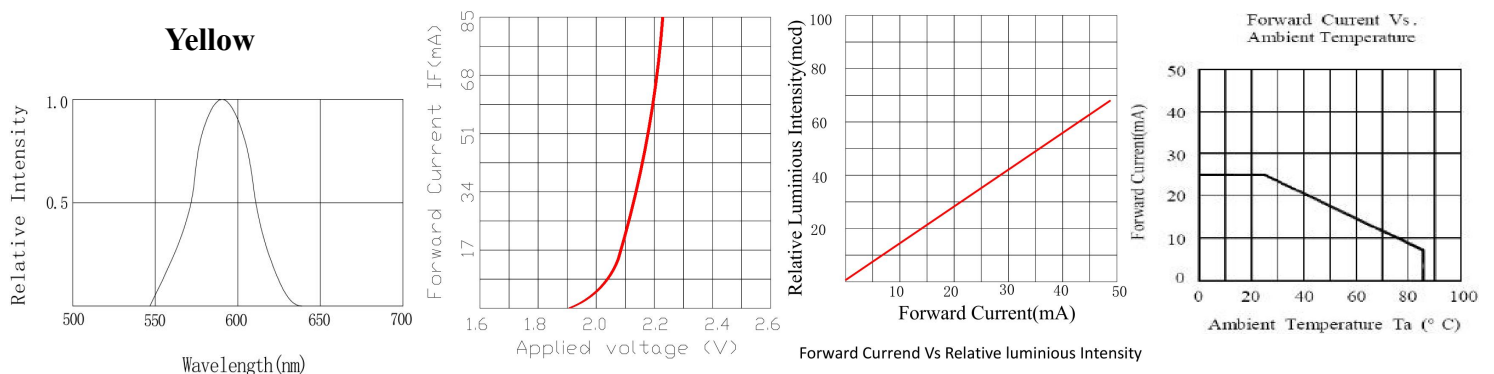
Parameter	Symbol	Condition	Color	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F=20\text{mA}$	Green Yellow	1.8 1.8	2.2 2.2	2.6 2.4	V
Luminous Intensity	I_v	$I_F=20\text{mA}$	Green Yellow	40 20	50 50	80 80	mcd
Reverse Current	I_R	$V_R=5\text{V}$	Green Yellow	-	-	10 10	μA
Peak Wave Length	λ_p	$I_F=20\text{mA}$	Green Yellow	-	-	-	nm
Dominant Wave Length	λ_d	$I_F=20\text{mA}$	Green Yellow	565 585	570 590	575 595	nm
Spectral Line Half-width	$\Delta\lambda$	$I_F=20\text{mA}$	Green Yellow	-	-	-	nm
Viewing Angle	$2\theta_{1/2}$	$I_F=20\text{mA}$	Green Yellow	-	50 70	-	deg

● Typical electro-optical characteristics curves

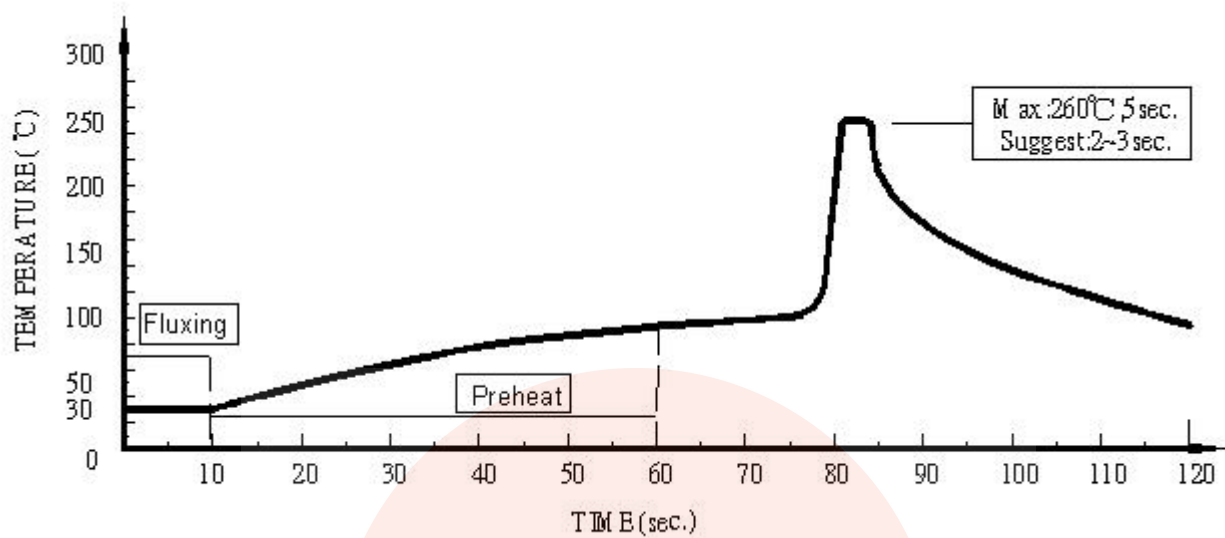
Green



Yellow



● DIP Soldering



1. Please avoid any external stress applied to the lead-frames and epoxy while the LEDs are at high temperature, especially during soldering
2. DIP soldering and hand soldering should not be done more than one time.
3. After soldering, avoid the epoxy lens from mechanical shock or vibration until the LEDs are back to room temperature.
4. Avoid rapid cooling during temperature ramp-down process
5. Although the soldering condition is recommended above, soldering at the lowest possible temperature is feasible for the LEDs

● IRON Soldering

A: Max: 350°C Within 3 sec. One time only.

B: The products of 3mm without flange, welding condition of flat plate PCB Max: 350°C

Within 2 sec. One time only

